

1. General description

The 74LVT241 high-performance BiCMOS device combines low static and dynamic power dissipation with high speed and high output drive.

This device is an octal buffer that is ideal for driving bus lines. The device features two output enables ($1\bar{O}E$, $2OE$), each controlling four of the 3-state outputs.

2. Features

- 3-state buffers
- Octal bus interface
- Input and output interface capability to systems at 5 V supply
- TTL input and output switching levels
- Output capability: +64 mA/-32 mA
- Latch-up protection exceeds 500 mA per JESD78 class II level A
- ESD protection:
 - HBM JESD22-A114E exceeds 2000 V
 - MM JESD22-A115-A exceeds 200 V
- Bus-hold data inputs eliminate the need for external pull-up resistors for unused inputs
- Live insertion/extraction permitted
- Power-up 3-state
- No bus current loading when output is tied to 5 V bus

3. Ordering information

Table 1. Ordering information

Type number	Package				Version
	Temperature range	Name	Description		
74LVT241D	-40 °C to +85 °C	SO20	plastic small outline package; 20 leads; body width 7.5 mm		SOT163-1
74LVT241PW	-40 °C to +85 °C	TSSOP20	plastic thin shrink small outline package; 20 leads; body width 4.4 mm		SOT360-1
74LVT241BQ	-40 °C to +85 °C	DHVQFN20	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 x 4.5 x 0.85 mm		SOT764-1

4. Functional diagram

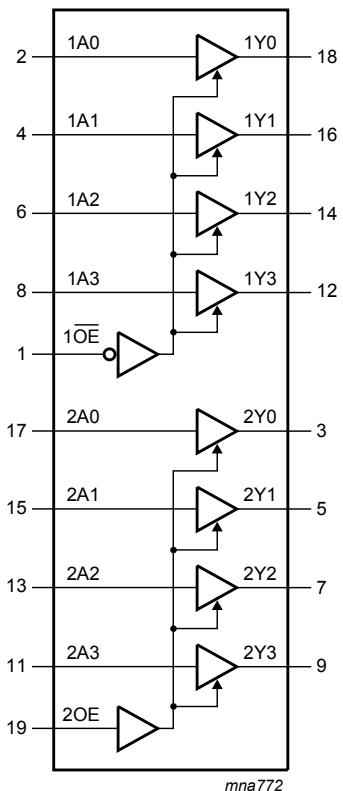


Fig. 1. Logic symbol

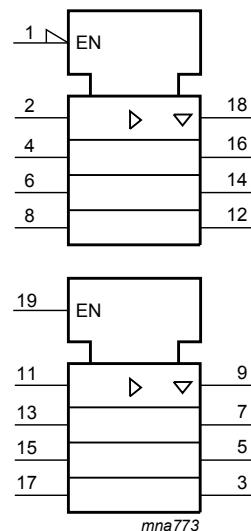


Fig. 2. IEC logic symbol

5. Pinning information

5.1. Pinning

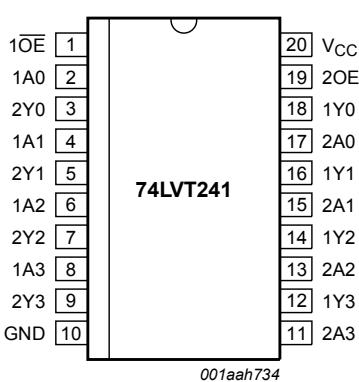
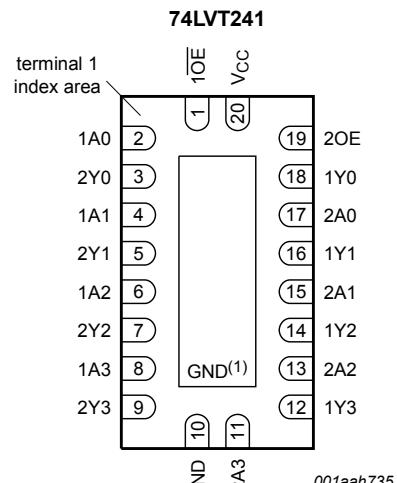


Fig. 3. Pin configuration for SO20 and TSSOP20



Transparent top view

(1) This is not a supply pin. The substrate is attached to this pad using conductive die attach material. There is no electrical or mechanical requirement to solder this pad. However, if it is soldered, the solder land should remain floating or be connected to GND.

Fig. 4. Pin configuration for DHVQFN20

5.2. Pin description

Table 2. Pin description

Symbol	Pin	Description
1OE	1	output enable input (active LOW)
1A0 to 1A3	2, 4, 6, 8	data input
2A0 to 2A3	17, 15, 13, 11	data input
GND	10	ground (0 V)
1Y0 to 1Y3	18, 16, 14, 12	data output
2Y0 to 2Y3	3, 5, 7, 9	data output
2OE	19	output enable input (active HIGH)
V _{CC}	20	supply voltage

6. Functional description

Table 3. Function table

H = HIGH voltage level; L = LOW voltage level; X = Don't care; Z = High impedance "OFF" state.

Inputs				Outputs	
1OE	2OE	1An	2An	1Yn	2Yn
L	H	L	L	L	L
L	H	H	H	H	H
H	L	X	X	Z	Z

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit	
V _{CC}	supply voltage		-0.5	+4.6	V	
V _I	input voltage		[1]	-0.5	+7.0	V
V _O	output voltage	output in OFF or HIGH state	[1]	-0.5	+7.0	V
I _{IK}	input clamping current	V _I < 0 V	-50	-	mA	
I _{OK}	output clamping current	V _O < 0 V	-50	-	mA	
I _O	output current	output in LOW state	-	128	mA	
		output in HIGH state	-64	-	mA	
T _{stg}	storage temperature		-65	+150	°C	
T _j	junction temperature		[2]	-	+150	°C
P _{tot}	total power dissipation	T _{amb} = -40 °C to +85 °C	[3]	-	500	mW

- [1] The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.
- [2] The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150 °C.
- [3] For SO20 package: above 70 °C derate linearly with 8 mW/K.
For TSSOP20 package: above 60 °C derate linearly with 5.5 mW/K.
For DHVQFN20 package: above 60 °C derate linearly with 4.5 mW/K.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		2.7	3.6	V
V _I	input voltage		0	5.5	V
I _{OH}	HIGH-level output current		-32	-	mA
I _{OL}	LOW-level output current	current duty cycle ≤ 50 %; f _i ≥ 1 kHz	-	64	mA
T _{amb}	ambient temperature	in free air	-40	+85	°C
Δt/ΔV	input transition rise and fall rate	output enabled	0	10	ns/V

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V); T_{amb} = -40 °C to +85 °C.

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit	
V_{IK}	input clamping voltage	$V_{CC} = 2.7 \text{ V}$; $I_{IK} = -18 \text{ mA}$	-1.2	-0.9	-	V	
V_{IH}	HIGH-level input voltage		2.0	-	-	V	
V_{IL}	LOW-level input voltage		-	-	0.8	V	
V_{OH}	HIGH-level output voltage	$V_{CC} = 2.7 \text{ V}$ to 3.6 V ; $I_{OH} = -100 \mu\text{A}$	$V_{CC} - 0.2$	$V_{CC} - 0.1$	-	V	
		$V_{CC} = 2.7 \text{ V}$; $I_{OH} = -8 \text{ mA}$	2.4	2.5	-	V	
		$V_{CC} = 3.0 \text{ V}$; $I_{OH} = -32 \text{ mA}$	2.0	2.2	-	V	
V_{OL}	LOW-level output voltage	$V_{CC} = 2.7 \text{ V}$; $I_{OL} = 100 \mu\text{A}$		0.1	0.2	V	
		$V_{CC} = 2.7 \text{ V}$; $I_{OL} = 24 \text{ mA}$	-	0.3	0.5	V	
		$V_{CC} = 3.0 \text{ V}$; $I_{OL} = 16 \text{ mA}$	-	0.25	0.4	V	
		$V_{CC} = 3.0 \text{ V}$; $I_{OL} = 32 \text{ mA}$	-	0.3	0.5	V	
		$V_{CC} = 3.0 \text{ V}$; $I_{OL} = 64 \text{ mA}$	-	0.4	0.55	V	
I_I	input leakage current	control and data pins					
		$V_{CC} = 0 \text{ V}$ or 3.6 V ; $V_I = 5.5 \text{ V}$	-	1	10	μA	
		control pins					
		$V_{CC} = 3.6 \text{ V}$; $V_I = V_{CC}$ or GND	-	0.1	± 1	μA	
		data pins [2]					
		$V_{CC} = 3.6 \text{ V}$; $V_I = V_{CC}$	-	0.1	1	μA	
		$V_{CC} = 3.6 \text{ V}$; $V_I = 0 \text{ V}$	-5	-1	-	μA	
I_{OFF}	power-off leakage current	$V_{CC} = 0 \text{ V}$; V_I or $V_O = 0 \text{ V}$ to 4.5 V	-	1	± 100	μA	
I_{BHL}	bus hold LOW current	$V_{CC} = 3.0 \text{ V}$; $V_I = 0.8 \text{ V}$	75	150	-	μA	
I_{BHH}	bus hold HIGH current	$V_{CC} = 3.0 \text{ V}$; $V_I = 2.0 \text{ V}$	-	-150	-75	μA	
I_{BHLO}	bus hold LOW overdrive current	$V_{CC} = 3.6 \text{ V}$; $V_I = 0 \text{ V}$ to 3.6 V	[3]	500	-	μA	
I_{BHHO}	bus hold HIGH overdrive current	$V_{CC} = 3.6 \text{ V}$; $V_I = 0 \text{ V}$ to 3.6 V	[3]	-	-500	μA	
I_{LO}	output leakage current	$V_O = 5.5 \text{ V}$; $V_{CC} = 3.0 \text{ V}$; output HIGH	-	60	125	μA	
$I_{O(pu/pd)}$	power-up/power-down output current	$V_{CC} \leq 1.2 \text{ V}$; $V_O = 0.5 \text{ V}$ to V_{CC} ; $V_I = \text{GND}$ or V_{CC} ; $1\overline{OE}$, $2OE$ = don't care	[4]	± 1	± 100	μA	
I_{OZ}	OFF-state output current	$V_{CC} = 3.6 \text{ V}$; $V_O = 3.0 \text{ V}$	-	1	5	μA	
		$V_{CC} = 3.6 \text{ V}$; $V_O = 0.5 \text{ V}$	-5	-1	-	μA	
I_{CC}	supply current	$V_{CC} = 3.6 \text{ V}$; $V_I = V_{CC}$ or GND; $I_O = 0 \text{ A}$					
		outputs HIGH	-	0.12	0.19	mA	
		outputs LOW	-	3	12	mA	
		outputs disabled [5]	-	0.12	0.19	mA	
ΔI_{CC}	additional supply current	per input pin; $V_{CC} = 3.0 \text{ V}$ to 3.6 V ; one input = $V_{CC} - 0.6 \text{ V}$ other inputs at V_{CC} or GND	[6]	-	0.1	0.25	mA
C_I	input capacitance	$1\overline{OE}$ and $2OE$ inputs; outputs disabled; $V_I = 0 \text{ V}$ or 3.0 V	-	4	-	pF	

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
C _{I/O}	input/output capacitance	at input/output data pins, outputs disabled; V _{I/O} = 0 V or 3.0 V	-	8	-	pF

[1] All typical values are measured at T_{amb} = 25 °C.
 [2] Unused pins at V_{CC} or GND.
 [3] This is the bus hold overdrive current required to force the input to the opposite logic state.
 [4] This parameter is valid for any V_{CC} between 0 V and 1.2 V with a transition time of up to 10 ms.
 From V_{CC} = 1.2 V to V_{CC} = 3.3 V ± 0.3 V a transition time of 100 ms is permitted. This parameter is valid for T_{amb} = +25 °C only.
 [5] I_{CC} with the outputs disabled is measured with outputs pulled to V_{CC} or GND.
 [6] This is the increase in supply current for each input at the specified voltage level other than V_{CC} or GND.

10. Dynamic characteristics

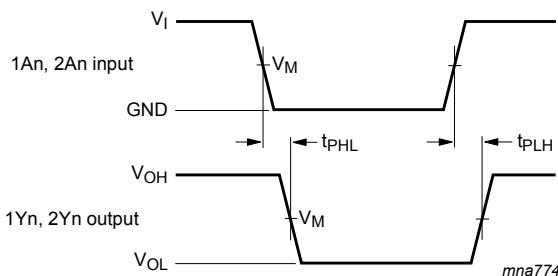
Table 7. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V). For test circuit see [Fig. 8](#); T_{amb} = -40 °C to +85 °C.

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
t _{PLH}	LOW to HIGH propagation delay	1An to 1Yn, 2An to 2Yn; see Fig. 5				
		V _{CC} = 2.7 V	-	-	4.0	ns
		V _{CC} = 3.3 V ± 0.3 V	1.0	2.8	3.8	ns
t _{PHL}	HIGH to LOW propagation delay	1An to 1Yn, 2An to 2Yn; see Fig. 5				
		V _{CC} = 2.7 V	-	-	4.0	ns
		V _{CC} = 3.3 V ± 0.3 V	1.0	2.8	3.8	ns
t _{PZH}	OFF-state to HIGH propagation delay	1OE to 1Yn; see Fig. 6				
		V _{CC} = 2.7 V	-	-	5.0	ns
		V _{CC} = 3.3 V ± 0.3 V	1.0	3.2	4.4	ns
		2OE to 2Yn; see Fig. 7				
		V _{CC} = 2.7 V	-	-	5.6	ns
		V _{CC} = 3.3 V ± 0.3 V	1.0	3.8	5.1	ns
t _{PZL}	OFF-state to LOW propagation delay	1OE to 1Yn; see Fig. 6				
		V _{CC} = 2.7 V	-	-	4.9	ns
		V _{CC} = 3.3 V ± 0.3 V	1.0	3.1	4.3	ns
		2OE to 2Yn; see Fig. 7				
		V _{CC} = 2.7 V	-	-	5.4	ns
		V _{CC} = 3.3 V ± 0.3 V	1.0	3.8	5.0	ns
t _{PHZ}	HIGH to OFF-state propagation delay	1OE to 1Yn; see Fig. 6				
		V _{CC} = 2.7 V	-	-	5.4	ns
		V _{CC} = 3.3 V ± 0.3 V	2.0	3.6	5.2	ns
		2OE to 2Yn; see Fig. 7				
		V _{CC} = 2.7 V	-	-	5.0	ns
		V _{CC} = 3.3 V ± 0.3 V	1.0	3.1	4.5	ns
t _{PLZ}	LOW to OFF-state propagation delay	1OE to 1Yn; see Fig. 6				
		V _{CC} = 2.7 V	-	-	4.3	ns
		V _{CC} = 3.3 V ± 0.3 V	1.6	2.9	4.2	ns
		2OE to 2Yn; see Fig. 7				
		V _{CC} = 2.7 V	-	-	4.3	ns
		V _{CC} = 3.3 V ± 0.3 V	1.0	2.8	4.0	ns

[1] Typical values are measured at T_{amb} = 25 °C and V_{CC} = 3.3 V.

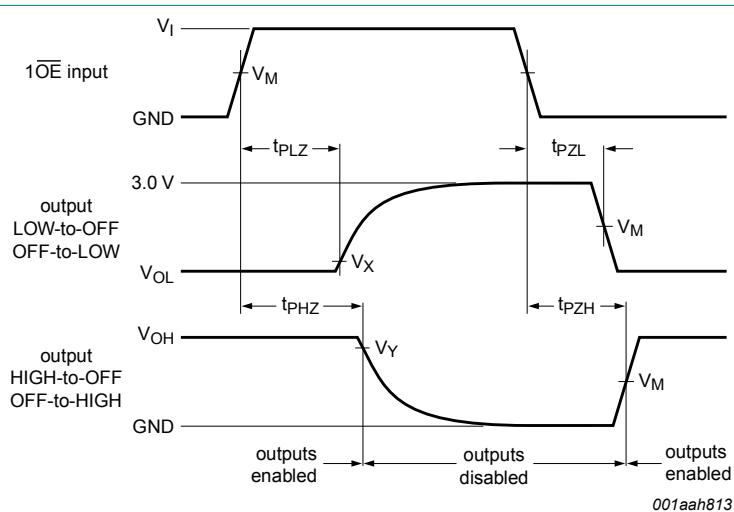
10.1. Waveforms and test circuit



See [Table 8](#) for measurement points.

V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

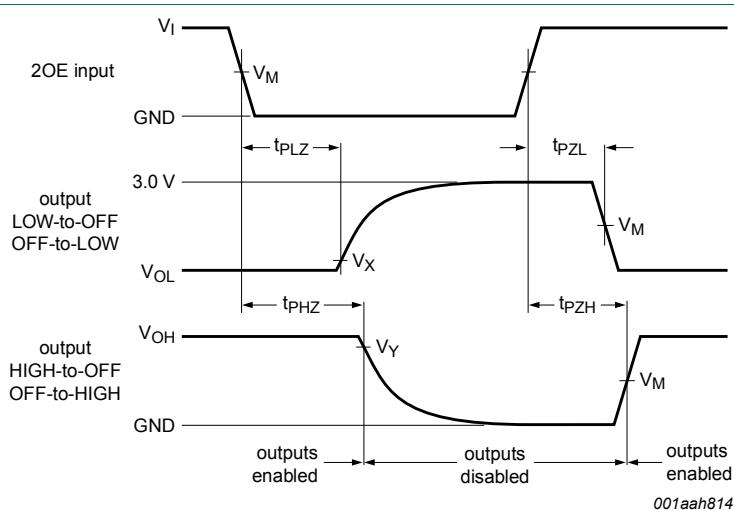
Fig. 5. Input (1An, 2An) to output (1Yn, 2Yn) propagation delays and output transition times



See [Table 8](#) for measurement points.

V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig. 6. 3-state output enable and disable times



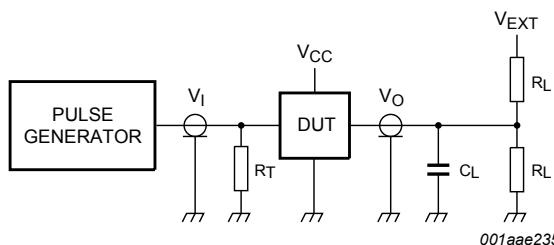
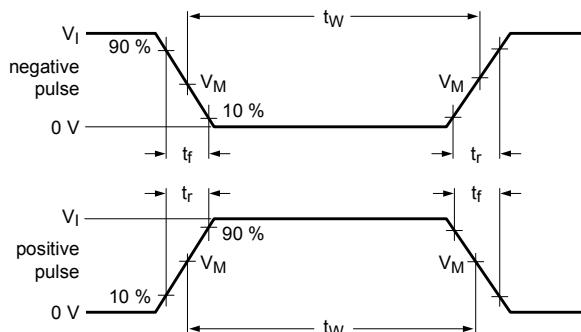
See [Table 8](#) for measurement points.

V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig. 7. 3-state output enable and disable times

Table 8. Measurement points

V _{CC}	Input	Output		
	V _M	V _X	V _Y	V _M
2.7 V to 3.6 V	1.5 V	V _{OL} + 0.3 V	V _{OH} - 0.3 V	1.5 V



Test data is given in [Table 9](#).

Definitions test circuit:

R_L = Load resistance.

C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to output impedance Z₀ of the pulse generator.

V_{EXT} = External voltage for measuring switching times.

Fig. 8. Test circuit for switching times

Table 9. Test data

Input				Load		V _{EXT}		
V _I	f _i	t _W	t _r , t _f	R _L	C _L	t _{PHZ} , t _{PZH}	t _{PLZ} , t _{PZL}	t _{PLH} , t _{PHL}
2.7 V	≤ 10 MHz	500 ns	≤ 2.5 ns	500 Ω	50 pF	GND	6 V	open

11. Package outline

SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1

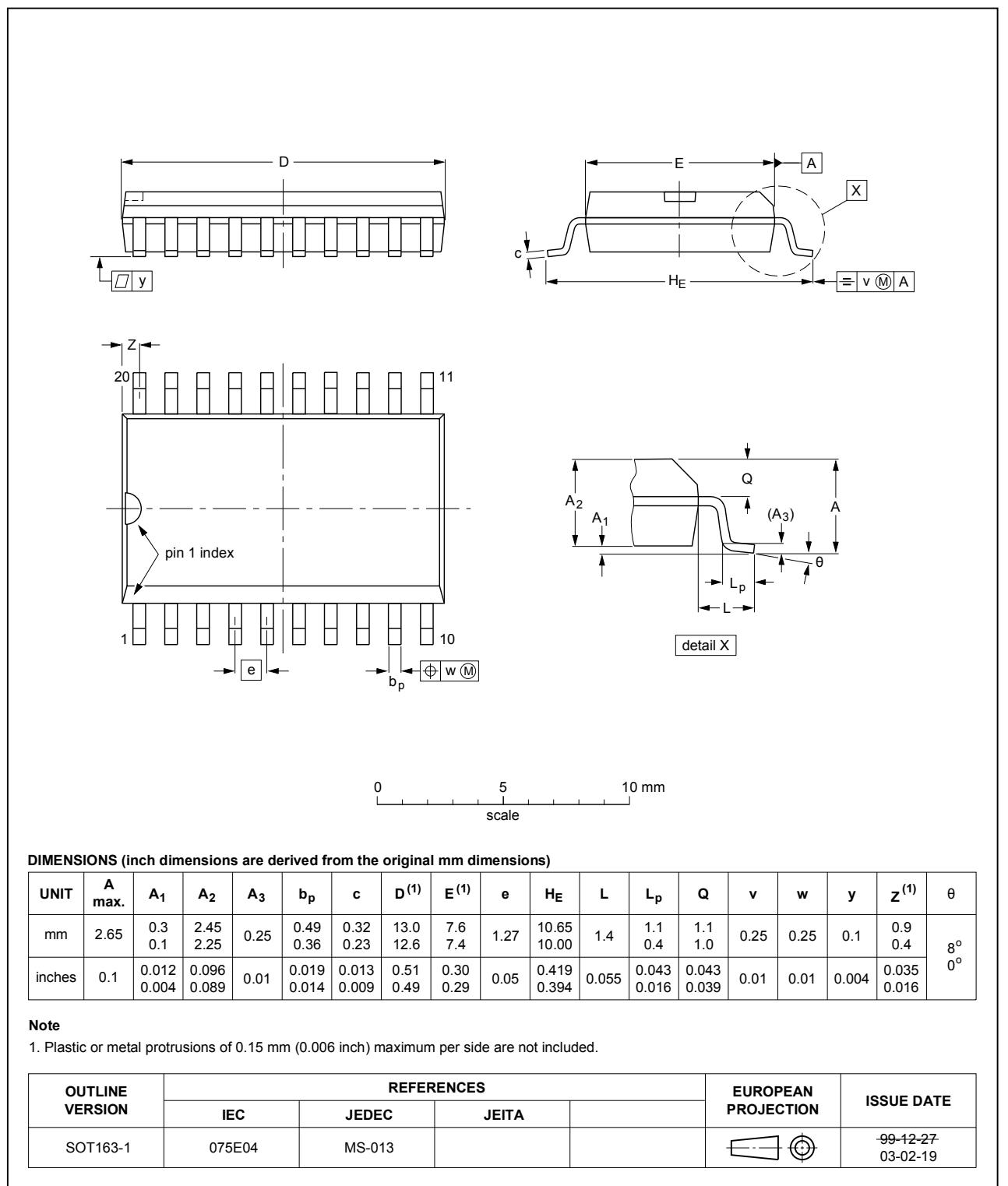
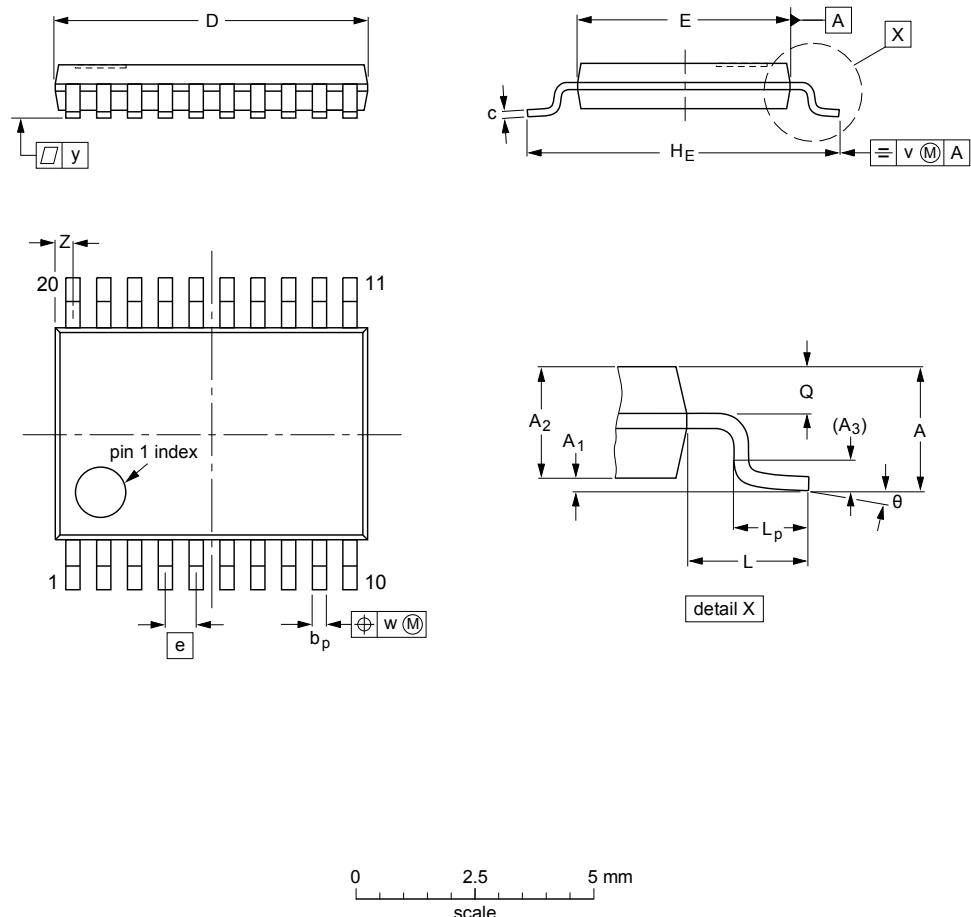


Fig. 9. Package outline SOT163-1 (SO20)

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽²⁾	e	H _E	L	L _p	Q	v	w	y	z ⁽¹⁾	θ
mm	1.1 0.05	0.15 0.80	0.95 0.25	0.25 0.19	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

Notes

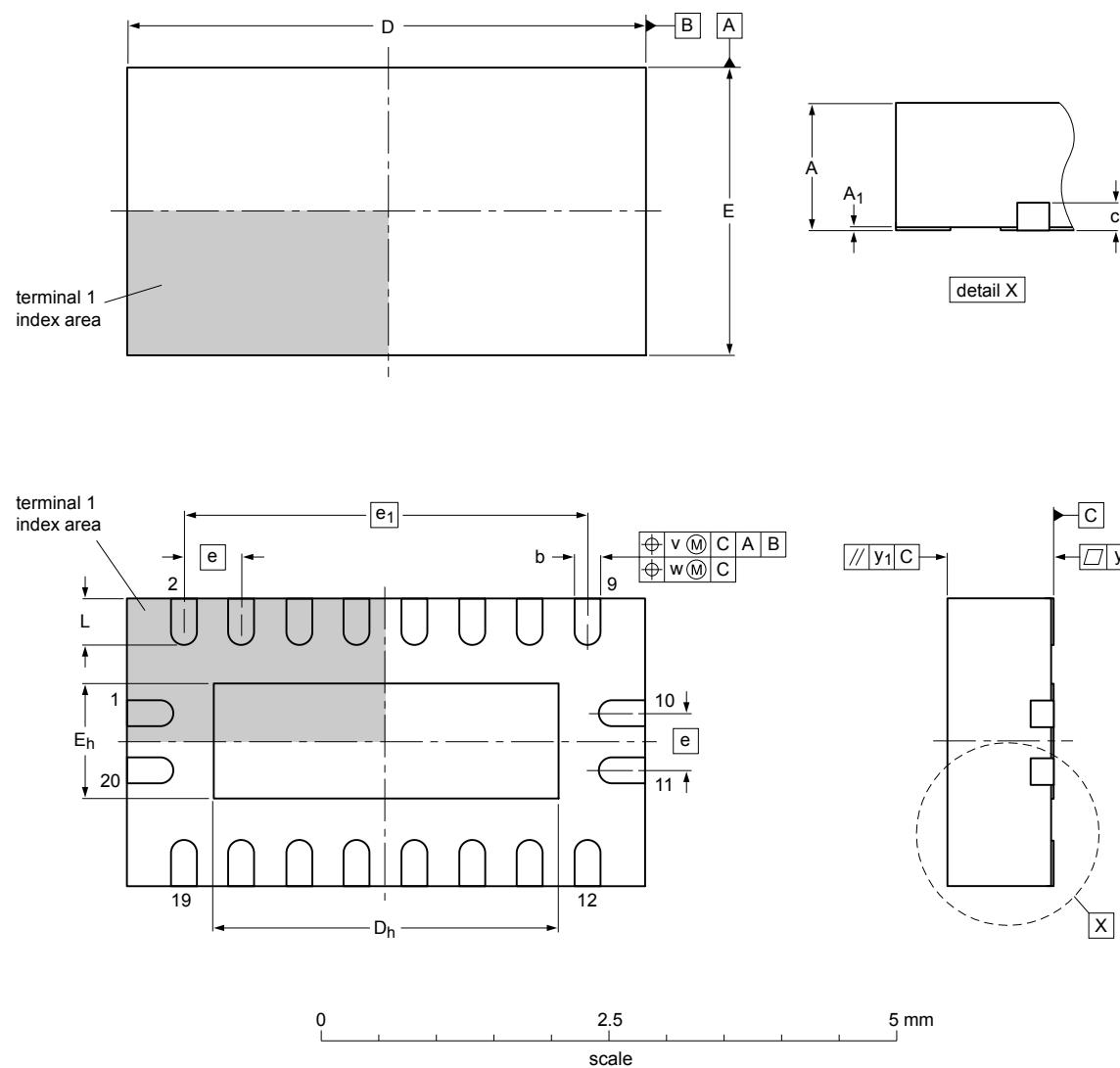
1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT360-1		MO-153				-99-12-27 03-02-19

Fig. 10. Package outline SOT360-1 (TSSOP20)

DHVQFN20: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads;
20 terminals; body 2.5 x 4.5 x 0.85 mm

SOT764-1



Dimensions (mm are the original dimensions)

Unit	A ⁽¹⁾	A ₁	b	c	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	e ₁	L	v	w	y	y ₁
mm	max	1.00	0.05	0.30	4.6	3.15	2.6	1.15	0.5						
mm	nom	0.90	0.02	0.25	0.2	4.5	3.00	2.5	1.00	0.5	3.5	0.4	0.1	0.05	0.1
mm	min	0.80	0.00	0.18	4.4	2.85	2.4	0.85	0.3						

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot764-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT764-1	---	MO-241	---		03-01-27 14-12-12

Fig. 11. Package outline SOT764-1 (DHVQFN20)

12. Abbreviations

Table 10. Abbreviations

Acronym	Description
BiCMOS	Bipolar Complementary Metal Oxide Semiconductor
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
TTL	Transistor-Transistor Logic

13. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVT241 v. 3	20190327	Product data sheet		74LVT241 v. 3
Modifications:	<ul style="list-style-type: none"> The format of this data sheet has been redesigned to comply with the identity guidelines of Nexperia. Legal texts have been adapted to the new company name where appropriate. Fig. 11: package outline drawing SOT764-1 (DHVQFN20) updated. Type number 74LVT241DB (SOT339-1) removed. 			
74LVT241 v. 3	20080507	Product data sheet	ECN07_046	74LVT241 v. 2
Modifications:	<ul style="list-style-type: none"> The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. Legal texts have been adapted to the new company name where appropriate. DHVQFN20 package added Section 3 and Section 11. 			
74LVT241 v. 2	19980219	Product specification	-	74LVT241 v. 1
74LVT241 v. 1	19960529	Product specification	-	-

14. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at <https://www.nexperia.com>.

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